TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (L²-π-MOSV)

2SK2376

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4-V gate drive

• Low drain–source ON resistance : R_{DS} (ON) = 13 m Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 40 \text{ S}$ (typ.) • Low leakage current : $I_{DSS} = 100 \text{ pA}$ (max) ($V_{DS} = 60 \text{ V}$)

• Enhancement mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	60	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	60	V	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	45	Α	
	Pulse (Note 1)	I _{DP}	180	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	100	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	701	mJ	
Avalanche current		I _{AR}	45	Α	
Repetitive avalanche	energy (Note 3)	E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature r	ange	T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C / W

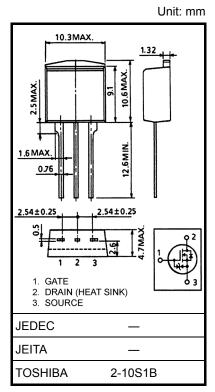
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 471 μ H, R_{G} = 25 Ω , I_{AR} = 45 A

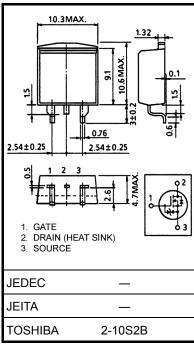
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



Weight: 1.5 g (typ.)



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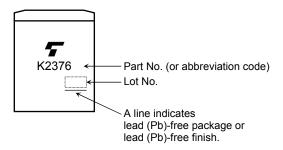
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	60	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 25 A	_	19	25	m0
			V _{GS} = 10 V, I _D = 25 A	_	13	17	mΩ
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 25 A	28	40	_	S
Input capacitano	e	C _{iss}			3350	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	550	_	
Output capacitance		Coss		_	1600	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{_{0V}} \stackrel{I_{D}=25A}{_{0V}} \stackrel{V_{OUT}}{_{1.2\Omega}} \stackrel{V_{DD}=30V}{_{0}} $ Duty $\leq 1\%$, $t_{W}=10\mu s$	_	25	_	
	Turn-on time	t _{on}		_	55	_	20
	Fall time	t _f		_	60	_	ns
	Turn-off time	t _{off}		_	180	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	110	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 45 \text{ A}$		70		nC
Gate-drain ("miller") charge		Q _{gd}			40	_	

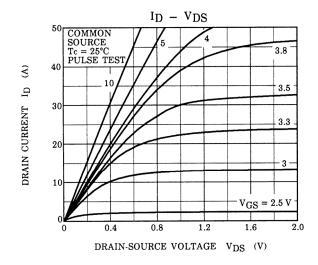
Source-Drain Ratings and Characteristics (Ta = 25°C)

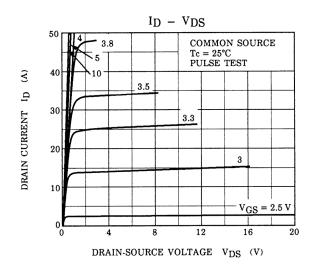
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	45	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_		_	180	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 45 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 45 A, V _{GS} = 0 V	1	120		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 50 A / μs	_	0.2	_	μC

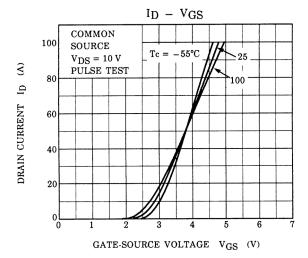
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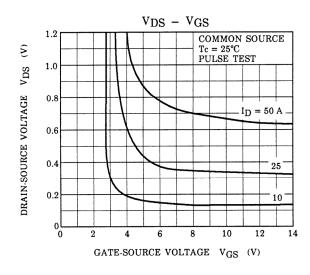


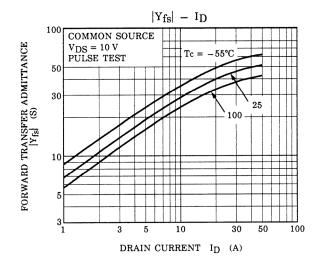
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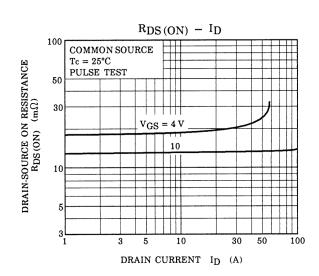




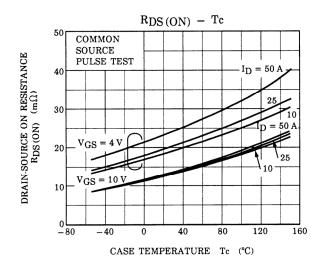


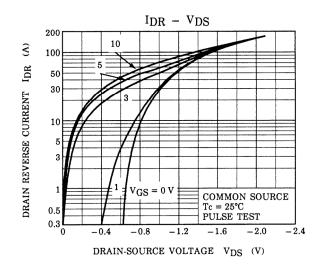


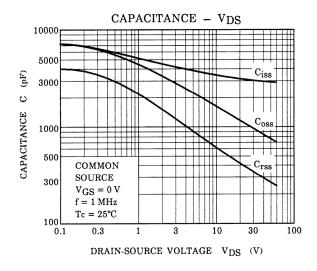


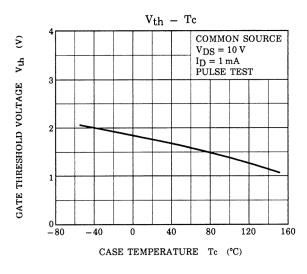


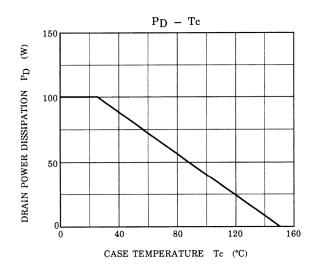
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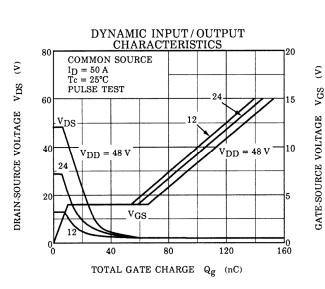




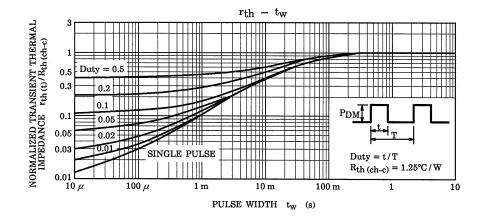


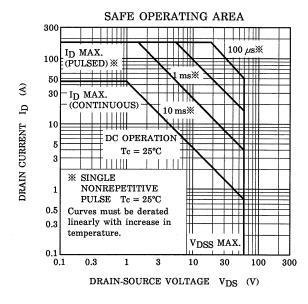


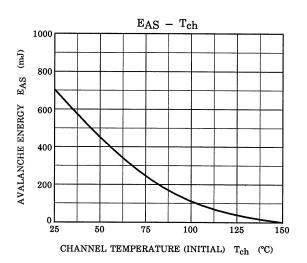


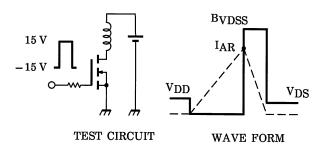


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$$\begin{split} RG &= 25~\Omega \\ V_{DD} &= 25~V,~L = 471~\mu H \end{split}$$

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$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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